

TITLE AMENDMENT

Please amend the title of the invention as follows,

SEALING APPARATUS FOR SEMICONDUCTOR WAFER, MOLD OF
SEALING APPARATUS, AND SEMICONDUCTOR WAFER AND METHOD FOR
~~MANUFACTURING SEMICONDUCTOR DEVICE BY USING SEALING~~
APPARATUS

SPECIFICATION AMENDMENT

Please replace the paragraph beginning at page 1, line 6, with the following rewritten paragraph:

-- This application claims the priority benefit of Japanese Patent Application No. 2001-089851, filed March 27, 2001, the entire disclosure of which is incorporated herein by reference. This application is a division of applicant's application Serial No. 10/103,889, filed March 25, 2002. --